

Oxidation of III-V semiconductors and applications

S. Calvez, N. Monvoisin, G. Lafleur, E. Hemsley, O. Stepanenko,
A. Monmayrant, H. Camon et G. Almuneau

GDR Oxyfun – 14/03/2023

Outline

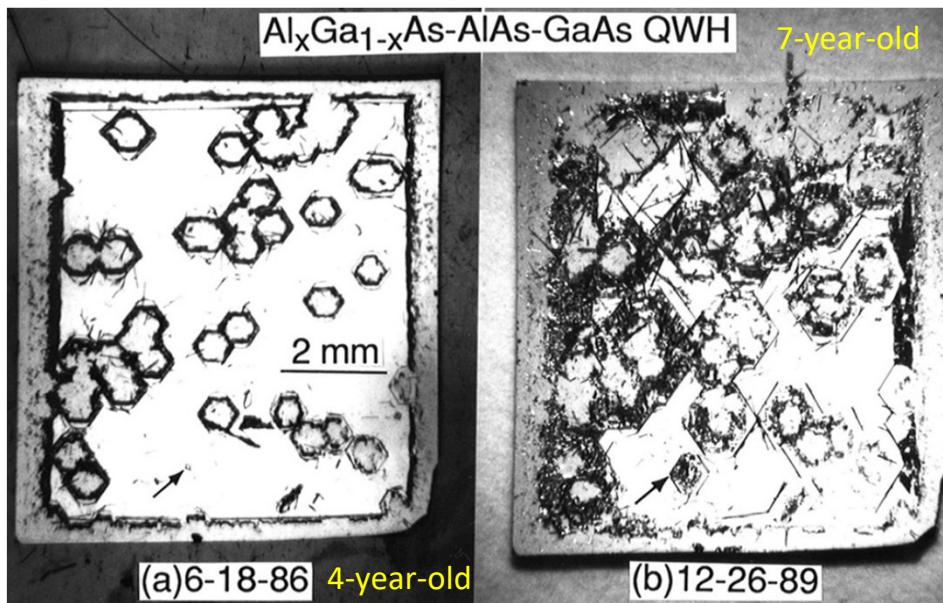
- Al-III-V-semiconductor oxidation
 - History
 - Applications
- Contributions from LAAS
 - In-situ monitoring
 - Oxidation Anisotropy
- Conclusions



Al-III-V-semiconductor oxidation history

Historical Perspective

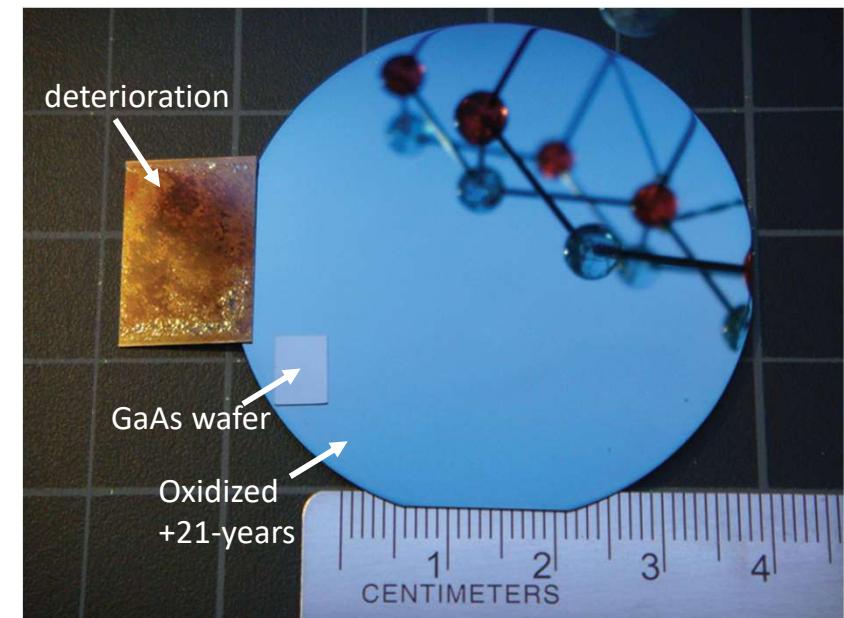
- > Oxidation of AlGaAs first observed in 1990



J.M. Dallesasse, N. Holonyak, *Appl. Phys. Lett.*, **56** (24), 2436 (1990)

- > Oxidation process = accelerated aging i.e. water+high temperature

J.M. Dallesasse, N. Holonyak, *Appl. Phys. Lett.*, **57** (24), 2844 (1990)



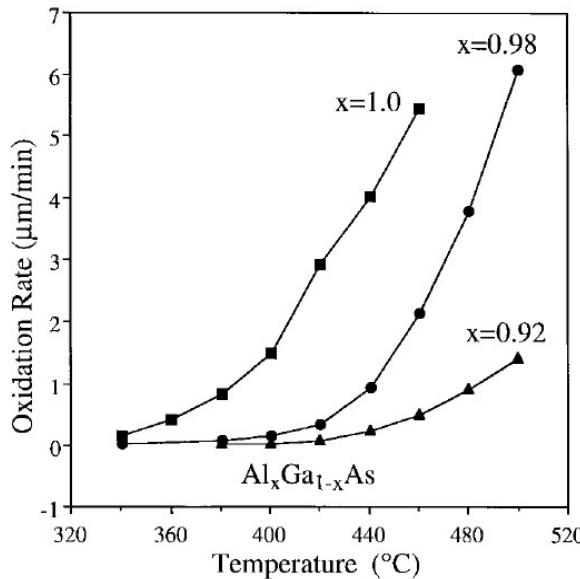
J.M. Dallesasse, N. Holonyak, *J. Appl. Phys.*, **113**, 051101 (2013)

High-Al layers degradation

III-V semiconductor oxidation

> Compositional selectivity in AlGaAs

■ Experiments



Oxidation rate drops exponentially as the Al concentration diminishes

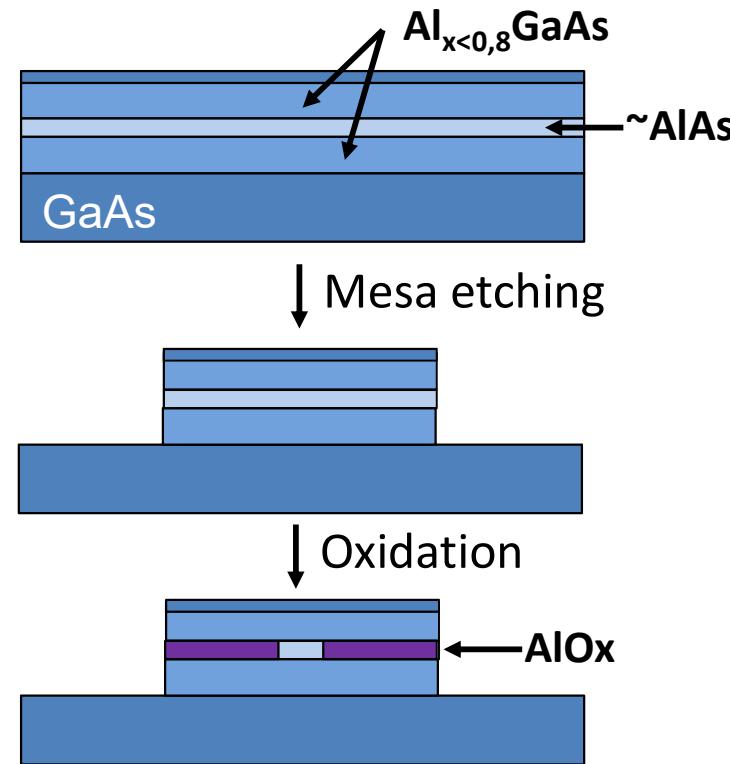
K.D. Choquette et al., *IEEE JSTQE*, **3**, 916 (1997)

■ Thermodynamics : C.I.H. Ashby et al, *J. Appl. Phys.*, **84**, 3134 (1997)

- $2\text{AlAs} + 6\text{H}_2\text{O} \rightarrow \text{Al}_2\text{O}_3 + \text{As}_2\text{O}_3 + 6\text{H}_2$ $\Delta G = -473 \text{ kJ/mol}$
- $\text{As}_2\text{O}_3(\text{l}) + 6\text{H} \rightarrow 2\text{As} + 3\text{H}_2\text{O(g)}$ $\Delta G = -1226 \text{ kJ/mol}$
- $2\text{GaAs} + 6\text{H}_2\text{O} \rightarrow \text{Ga}_2\text{O}_3 + \text{As}_2\text{O}_3 + 6\text{H}_2$ $\Delta G = 10 \text{ kJ/mol}$ unfavorable

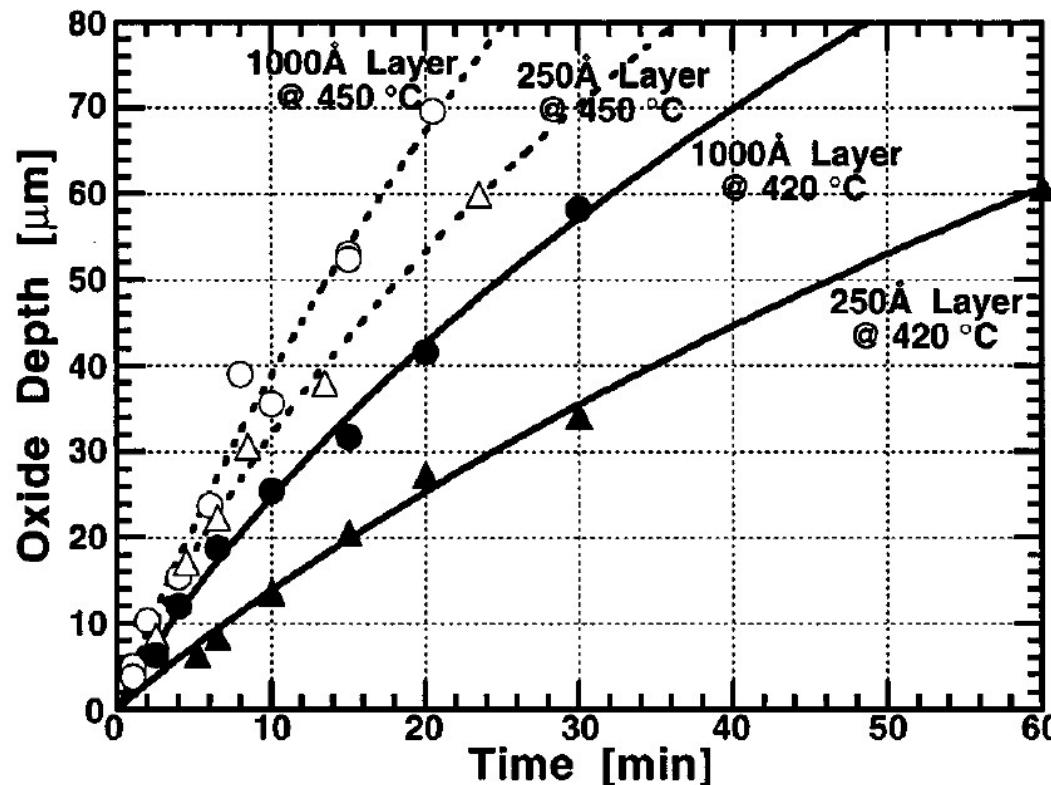
III-V semiconductor oxidation

> Selective (lateral) oxidation from an etched mesa



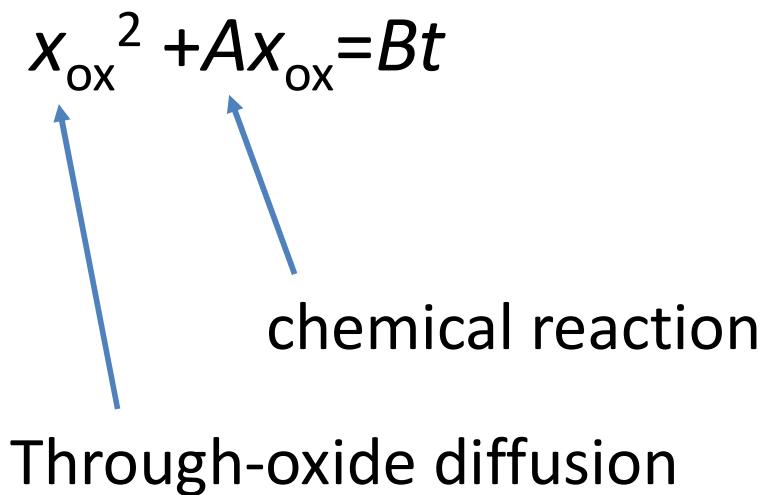
III-V semiconductor oxidation

> Length and thickness dependence



R.L. Naone et al., *J. Appl. Phys.*, **82**, 2277 (1997)

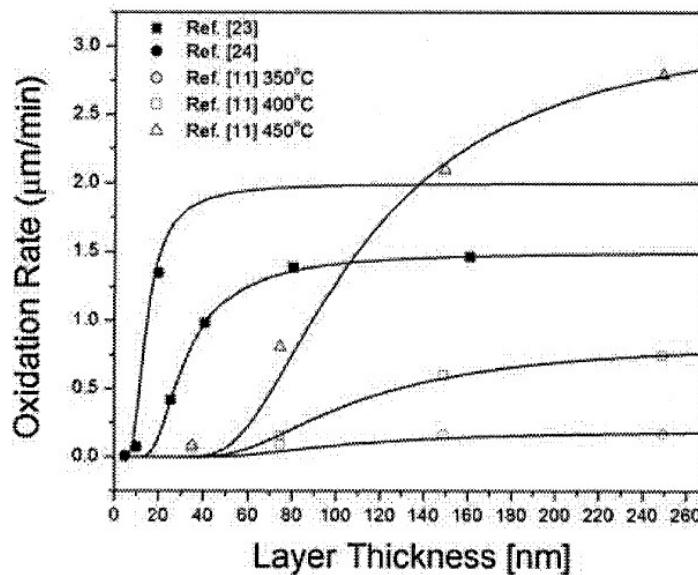
Extension of Si surface
oxidation model
(Deal & Grove, JAP, **36**, 3770 (1965))



III-V semiconductor oxidation : Exp. & Models

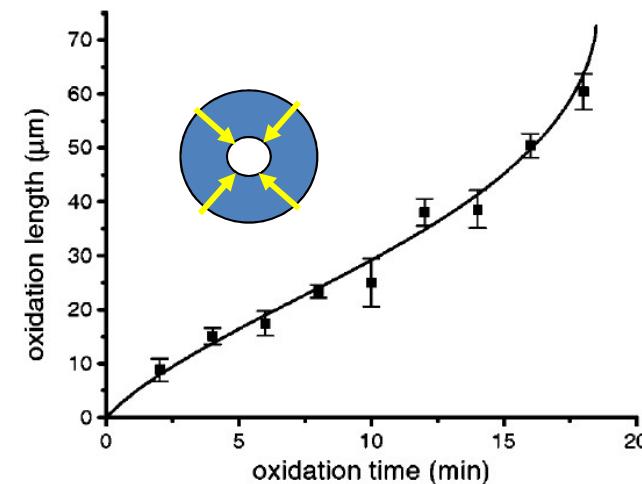
- > Extensions of Si-based (Deal & Grove, JAP, **36**, 3770 (1965)) oxidation model to include

- Lateral mesa geometry (\Rightarrow acceleration as surface reduces)



P.-C. Ku et al, *JSTQE*, **39**, 577 (2003)

- But always assumed the oxidation to be isotropic

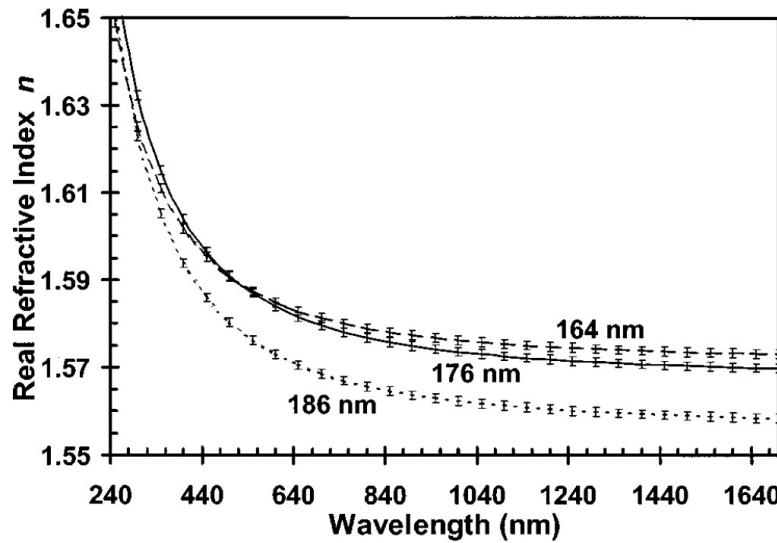


A.C. Alonzo et al, *JAP*, **84**, 6901 (1998)

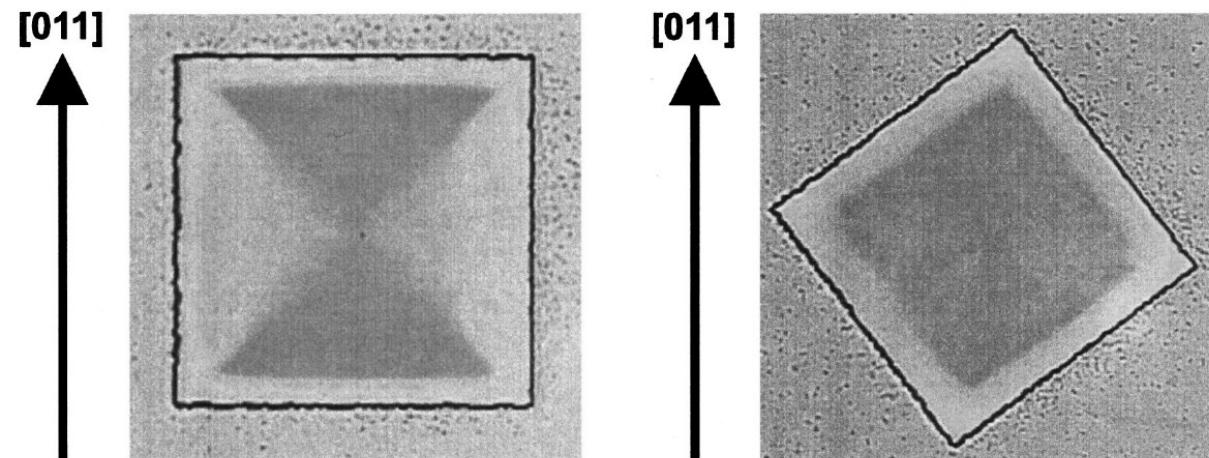
- Thickness-dependence (boundary interface/ grain size influence)

AlOx material properties

- > Al(Ga)Ox is an (electrically)-insulating material
- > Conversion of an optically high-index ($n \sim 2.9$) into a low-index material ($n \sim 1.6$)
- > 5 to 12% volumic contraction



K.J. Knopp et al., *Appl. Phys. Lett.*, **73**, 3512 (1997)

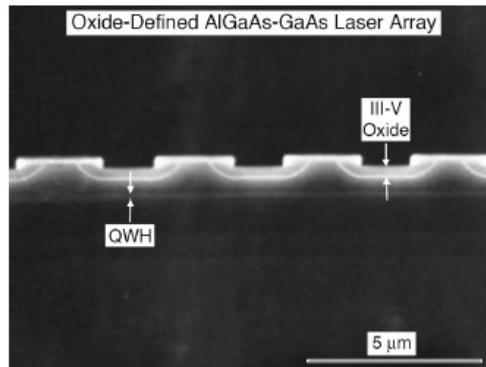


A.C. Alonzo et al., *J. Appl. Phys.*, **87**, 4594 (2000)

Al-III-V-semiconductor oxidation applications

Lasers using III-V oxidation

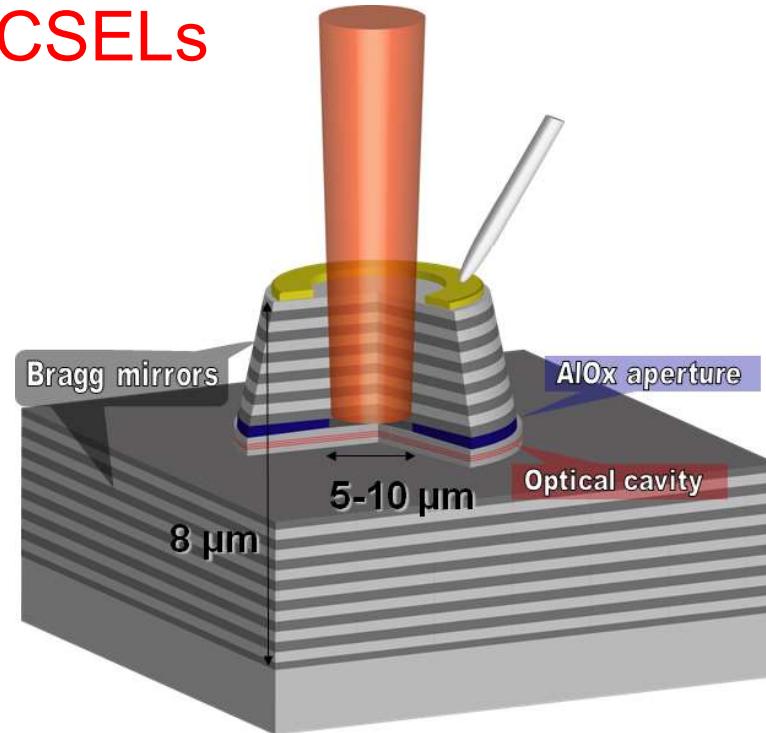
Edge Emitting lasers



J.M. Dallesasse et al., *APL*, **58**, 834 (1991)

Electrical confinement

VCSELs



D.L. Huffaker et al., *APL*, **65**, 97 (1994)

J.M. Dallesasse, *proc. IEEE*, **101**, 2234 (2013)

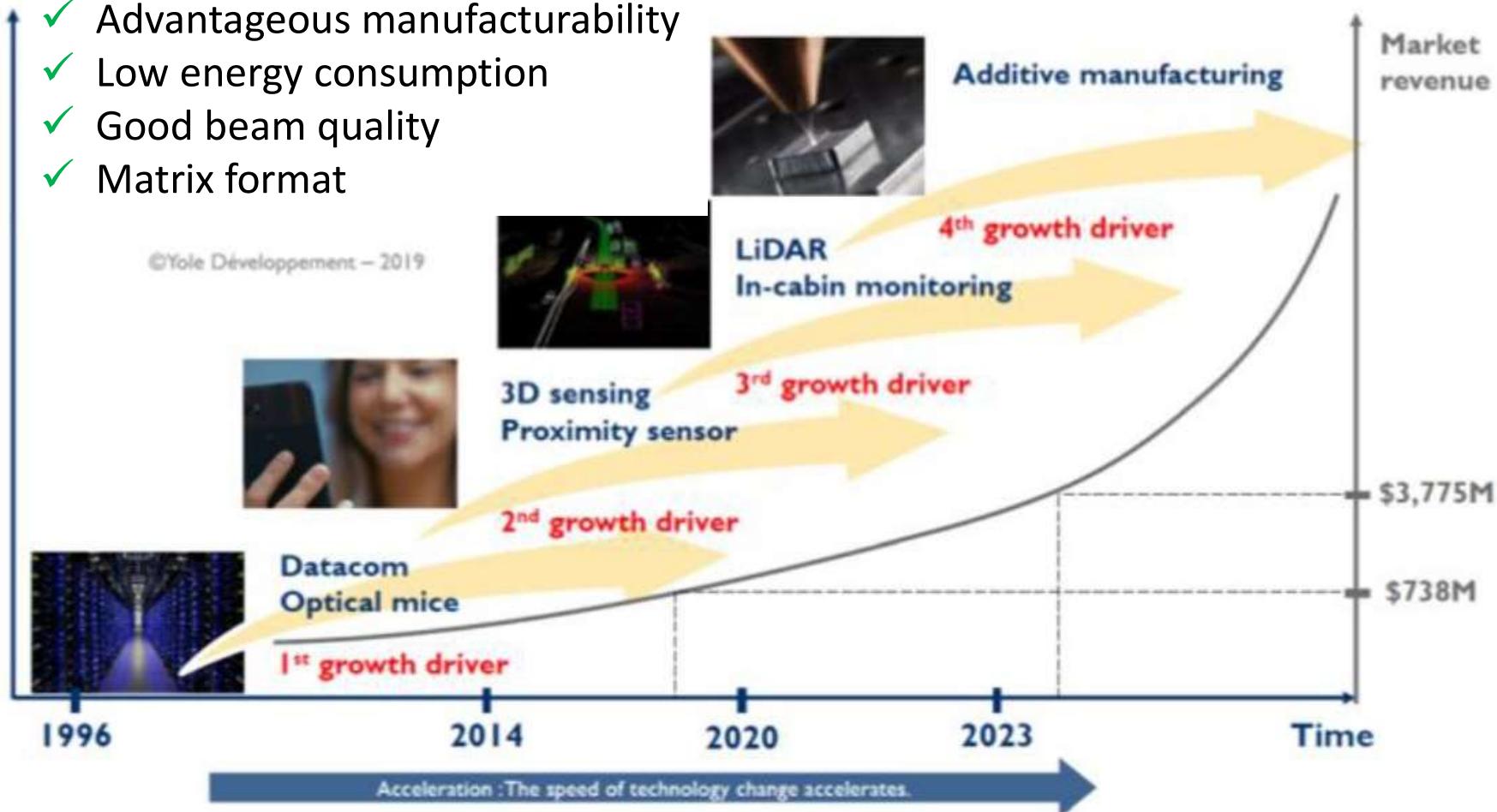
Electrical & Optical confinement

VCSEL market and uses

VCSEL benefits

- ✓ Advantageous manufacturability
- ✓ Low energy consumption
- ✓ Good beam quality
- ✓ Matrix format

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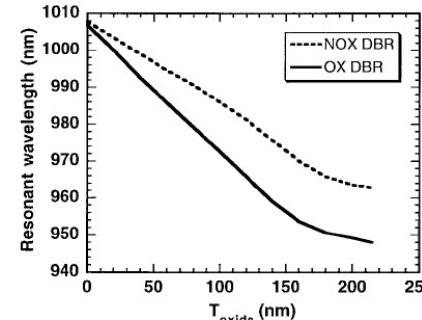
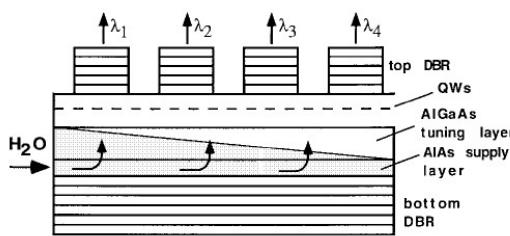


Trend | LEMON PHOTONICS VCSEL laser sensor chips have full production capability
Drivers that boost the growth of VCSEL market Source: 《VCSELs - Market and Technology Trends 2019》

III-V oxidation and VCSEL-related uses

Graded-thickness AlOx layer

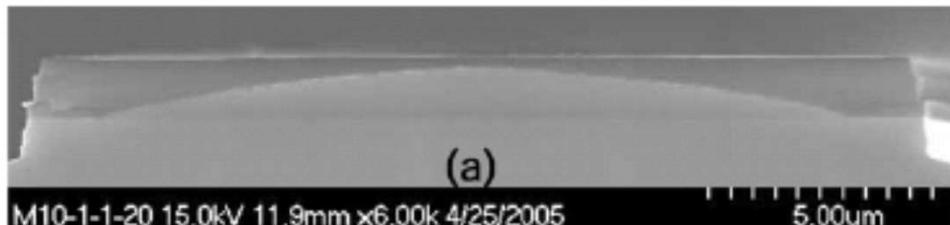
Multiwavelength VCSEL matrix



A. Fiore et al., *JQE*, **35** (4), 616 (1999)

$$\lambda_k = \frac{2 \cdot (n_{unox} L + (n_{ox} - n_{unox}) \cdot L_{ox})}{k}$$

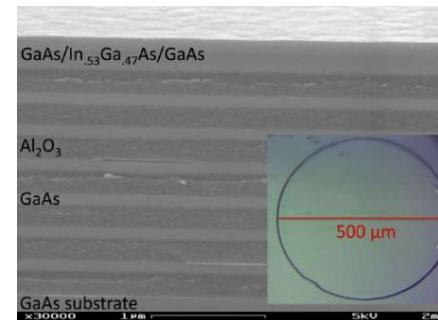
Microlenses



K.S. Chang et al., *IEEE PTL*, **18** (1), 121 (2006)

Wide-bandwidth mirrors

SESAMs



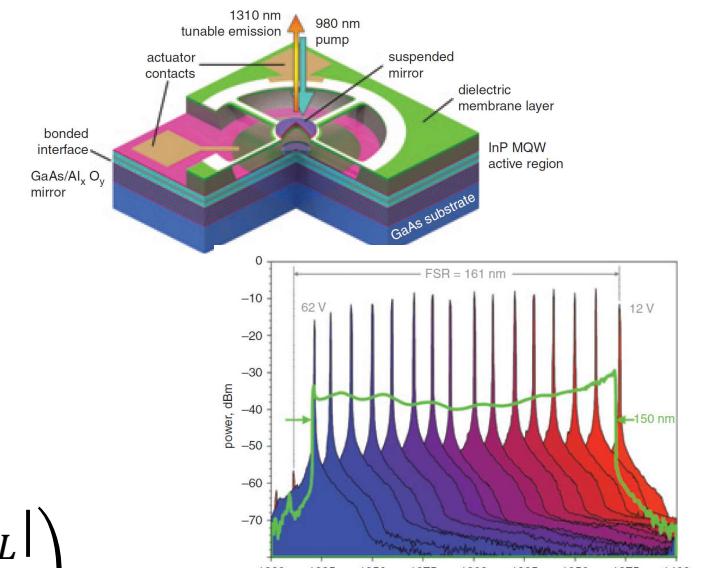
S.P. Nabanja et al., *JAP*, **113**, 161102 (2013)

$$\Delta\lambda = \frac{4}{\lambda\pi} \arcsin\left(\frac{|n_H - n_L|}{n_H + n_L}\right)$$

n_H=3.45 (GaAs)

n_L=2.9 (AlAs) 1.6 (AlOx)

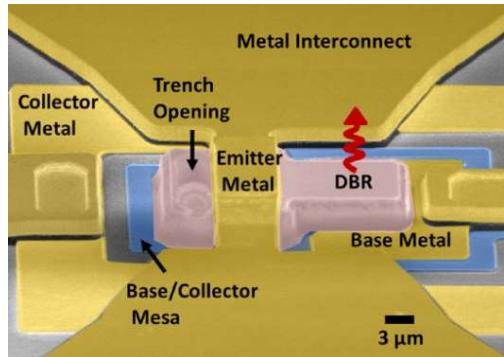
Widely-tunable VCSELs



V. Jayaraman et al., *Electron. Lett.*, **48** (14), 867 (2012)

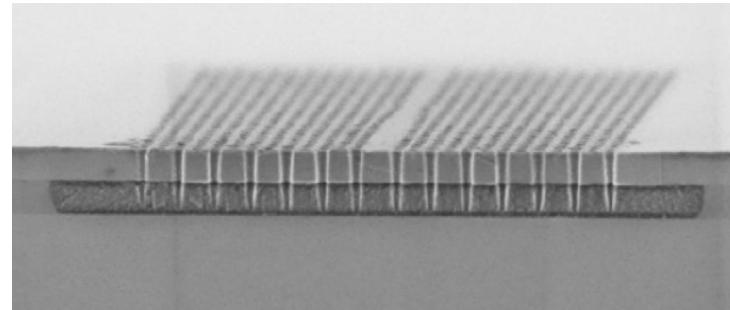
III-V oxidation for advanced lasers

Transistor lasers



M. Liu et al., *APL*, **114**, 163104 (2013)

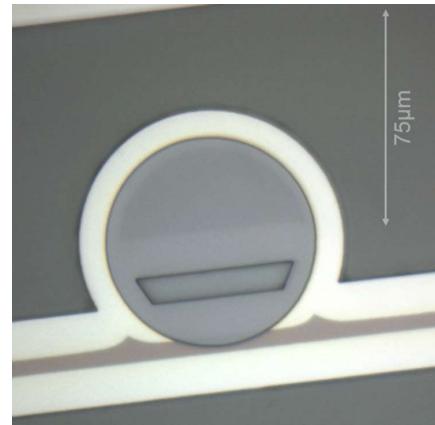
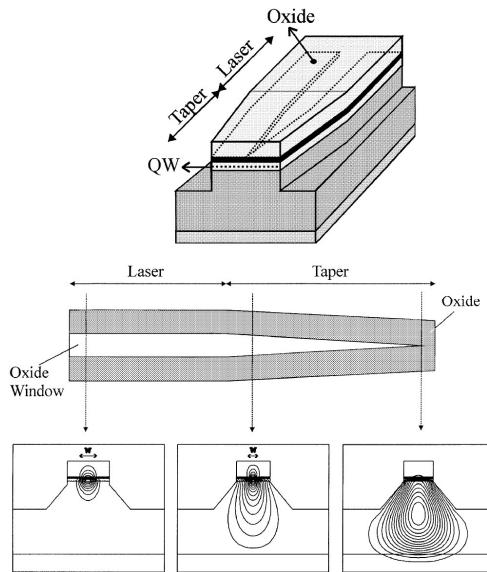
Photonic crystal waveguides



K. Welna et al., *Photon & Nanostruct.*, **11**, 139 (2013)

Photonic devices using III-V oxidation

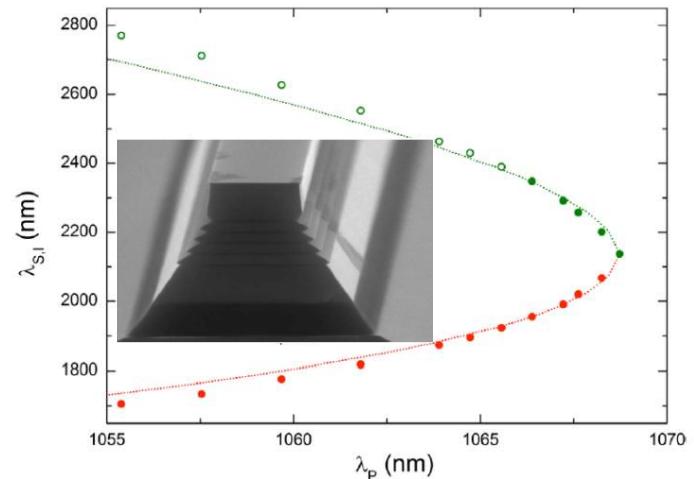
Photonic Integrated Circuits



S. Calvez et al., *PTL*, **27**, 982 (2015)

K. De Mesel et al., *JSTQE*, **8** (6), 1372 (2002)

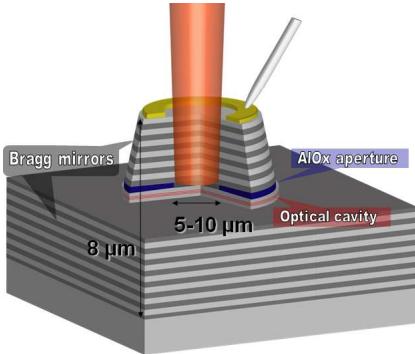
NLO waveguides



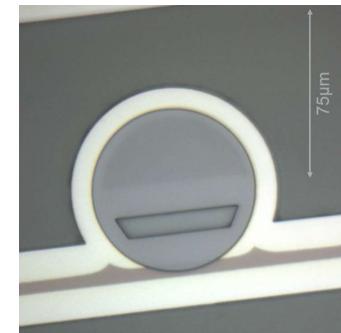
A. Fiore et al., *Nature*, **391**, 463 (1998)
M. Savanier et al., *APL*, **103**, 261105 (2013)

Contributions from LAAS

Need for controlled oxide apertures



D.L. Huffaker et al., *APL*, **65**, 97 (1994)
J.M. Dallesasse, *proc. IEEE*, **101**, 2234 (2013)



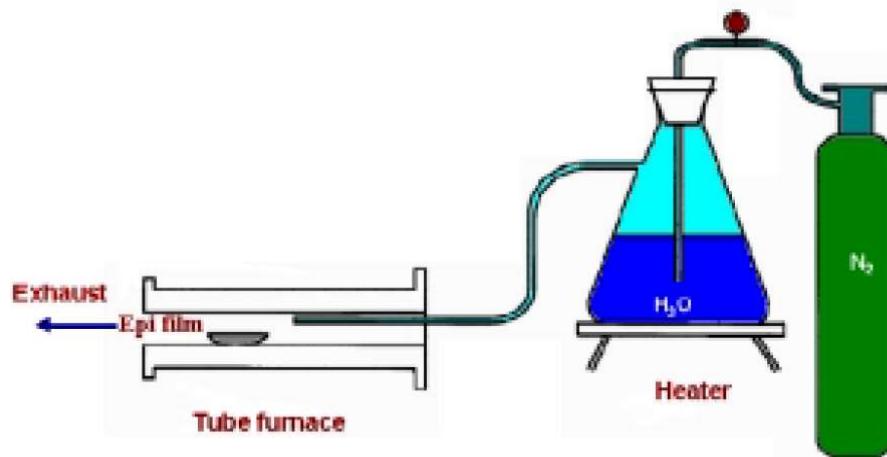
S. Calvez et al.,
PTL, **27**, 982
(2015)

- > Aperture size controls MM/SM
- > Singlemode devices
 - SM size limit is shape independent
 - Shape influence
 - Emission surface
 - Thermal/electrical resistance
 - Fibre-coupling efficiency
 - **Controlling the aperture shape and dimensions is important!**
- > Aperture shape defines propagation direction and modal content
- > Basic shapes
 - Straight waveguides
 - Curved waveguides

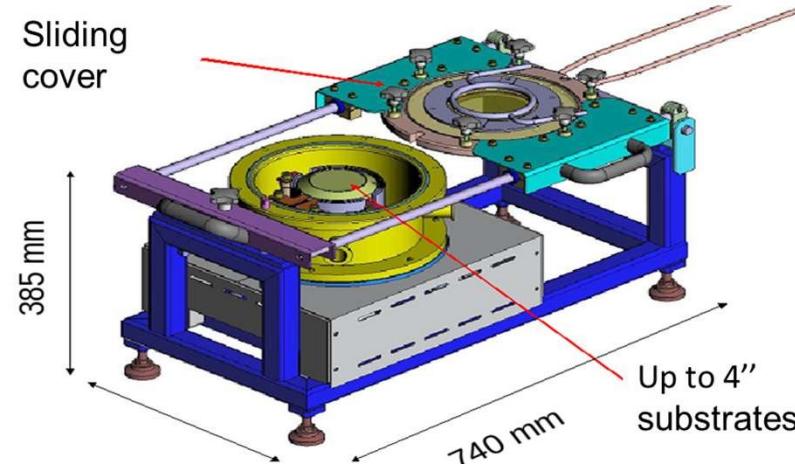


III-V oxidation furnace with monitoring

AlOx Furnace



- Dedicated oxidation furnace
 - Co-designed with AET Technologies / AlOxTec
 - Reduced pressure oxidation
 - Gas injectors instead of bubblers
 - Up to 4" wafers
 - Improved uniformity & reproducibility
- Optical view port for in-situ monitoring

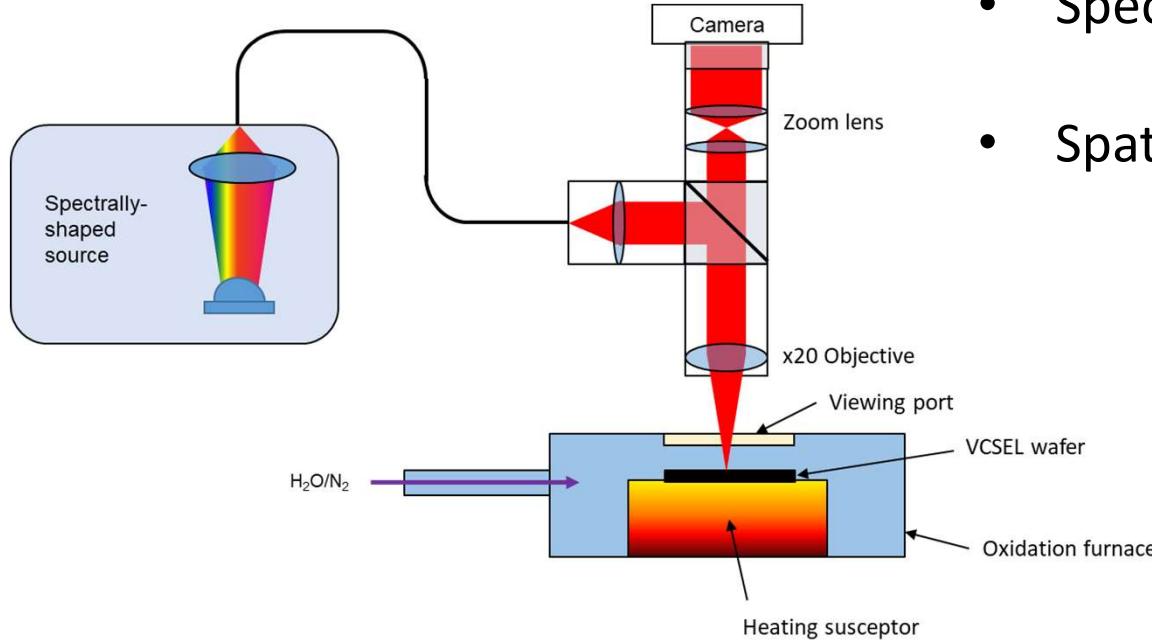


In-situ real-time monitoring

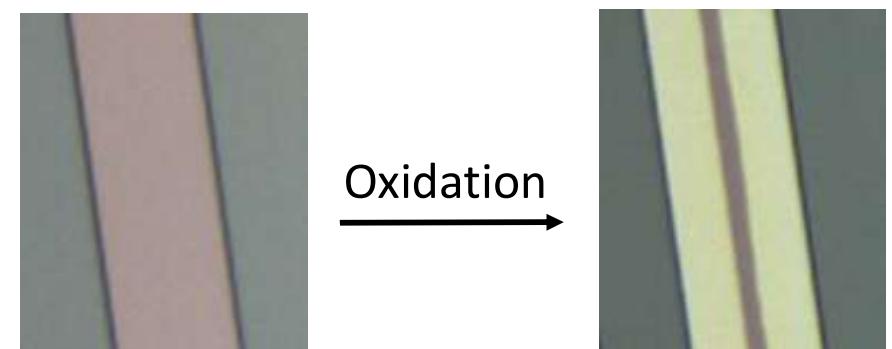
- Micro-reflectometry system
 - Change of refractive index upon oxidation
=> local change of reflectivity
 - NIR illumination (700-950nm)
 - Spectrally-resolved illumination

G. Almuneau et al, *Semicon. Sc. Technol.*, **23**, 105021 (2008)

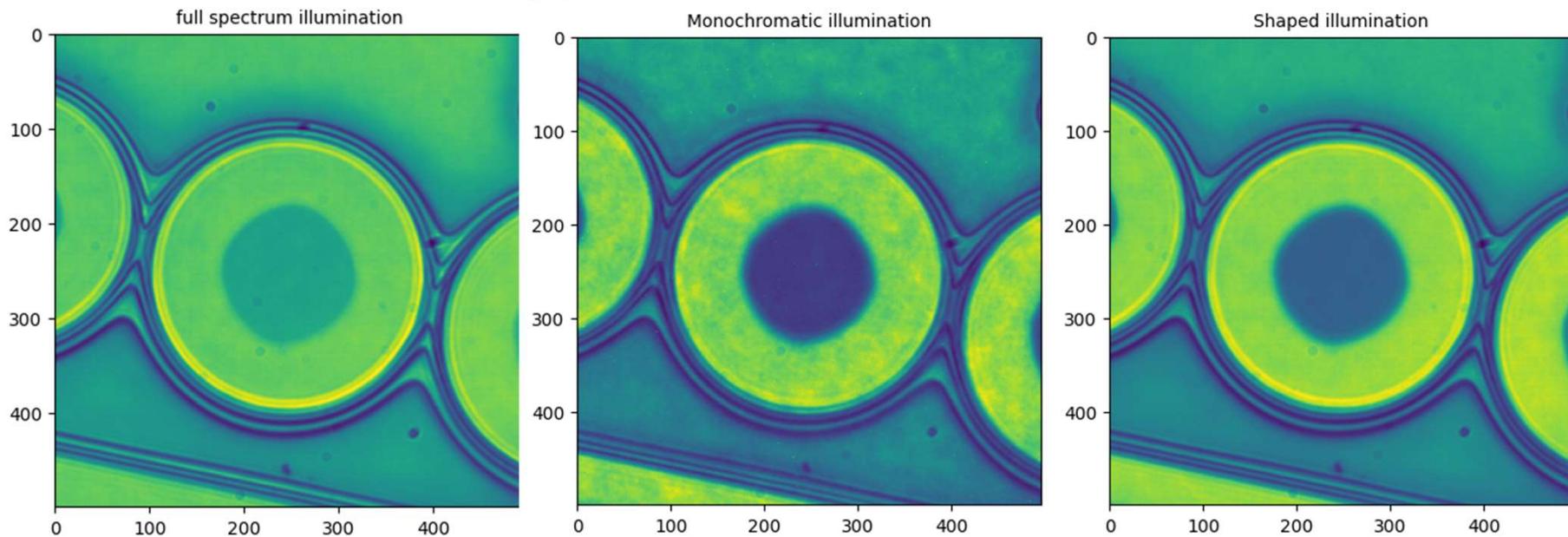
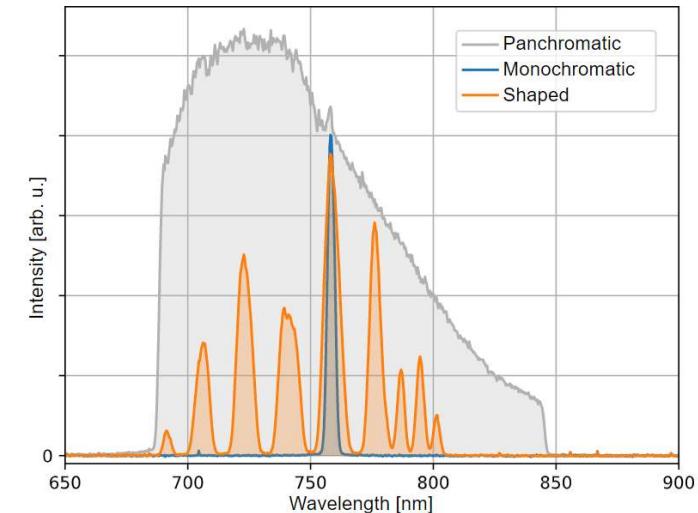
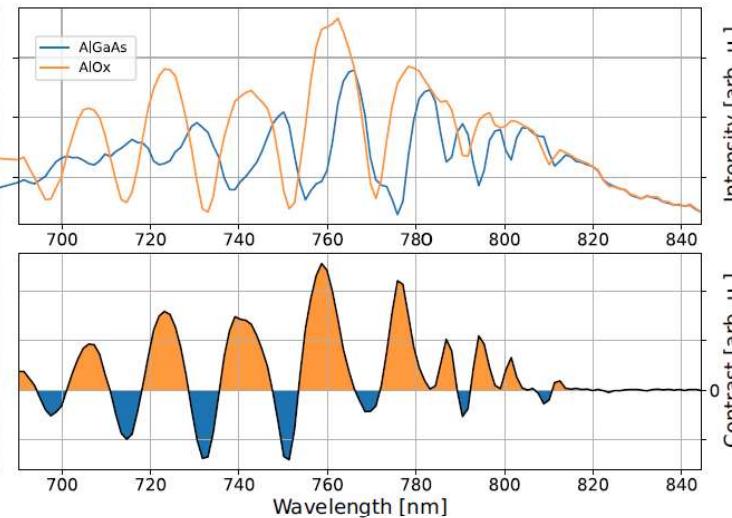
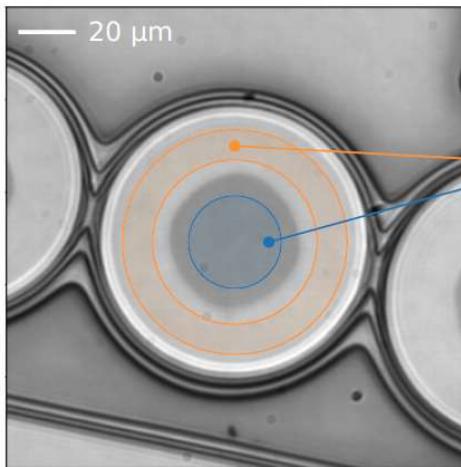
- Spectrally-shaped illumination
N. Monvoisin et al, *Opt. Express*, **31**, (2023)
- Spatial resolution $\sim 1\mu\text{m}$



G. Almuneau et al, *Semicon. Sc. Technol.*, **23**, 105021 (2008)



Oxidation monitoring

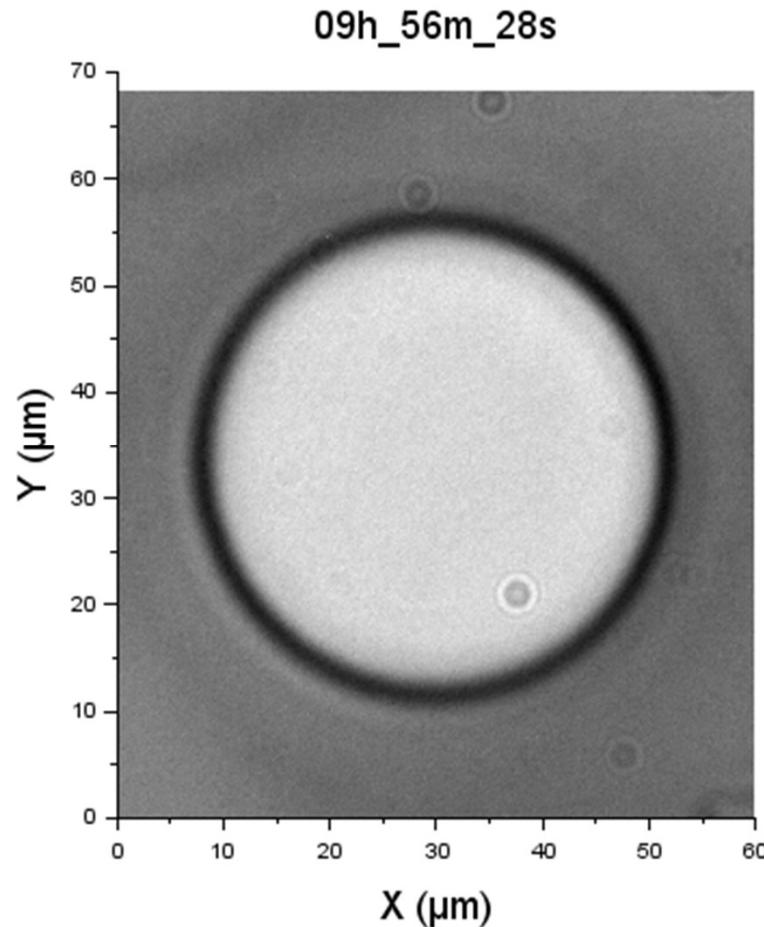


N. Monvoisin et al, *Opt. Express*, 31, (2023)

14/03/2023

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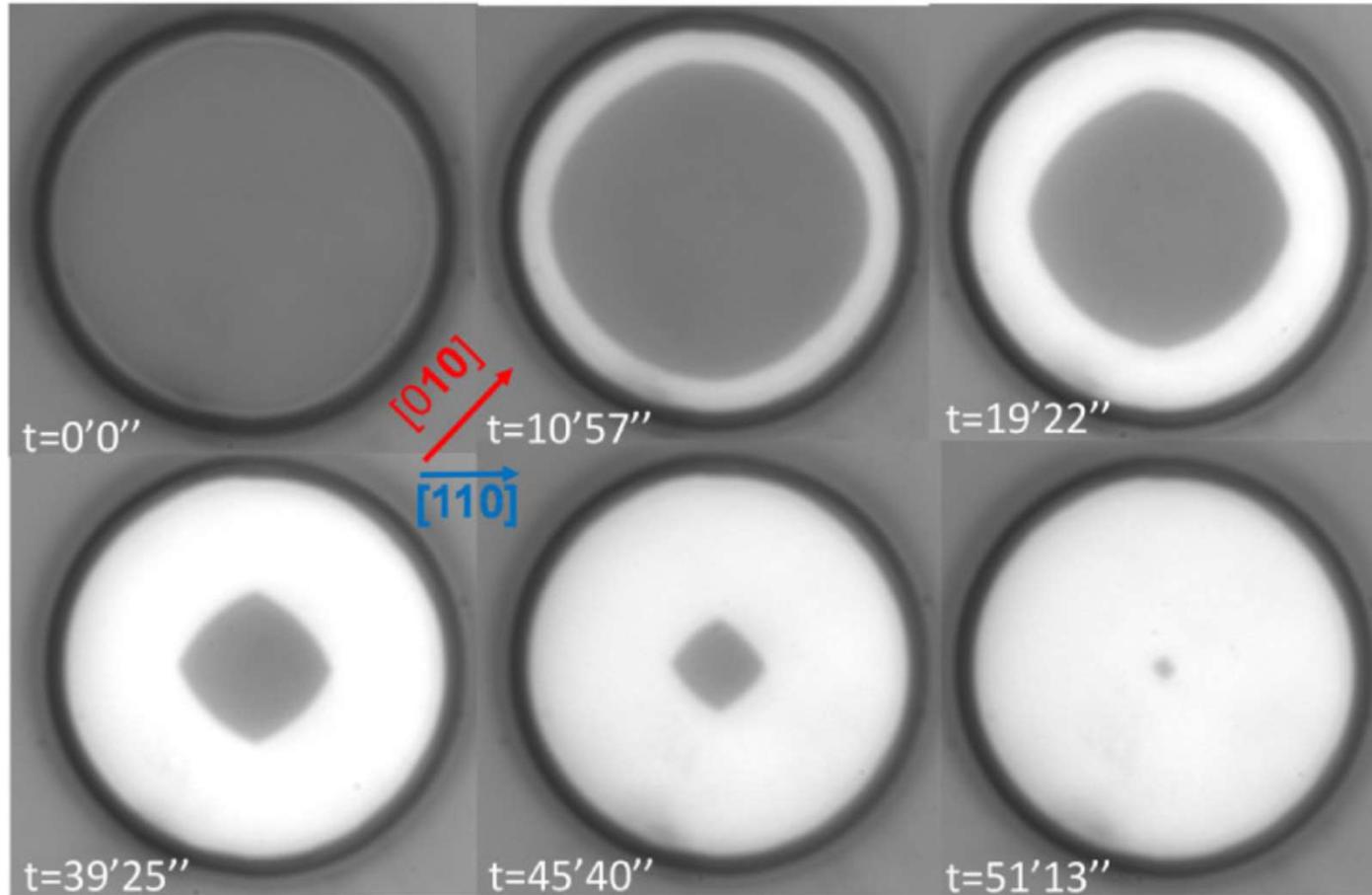
Oxidation monitoring



Benefits

- ✓ Improved industrial manufacturability
- ✓ Datasets for science

Oxidation anisotropy

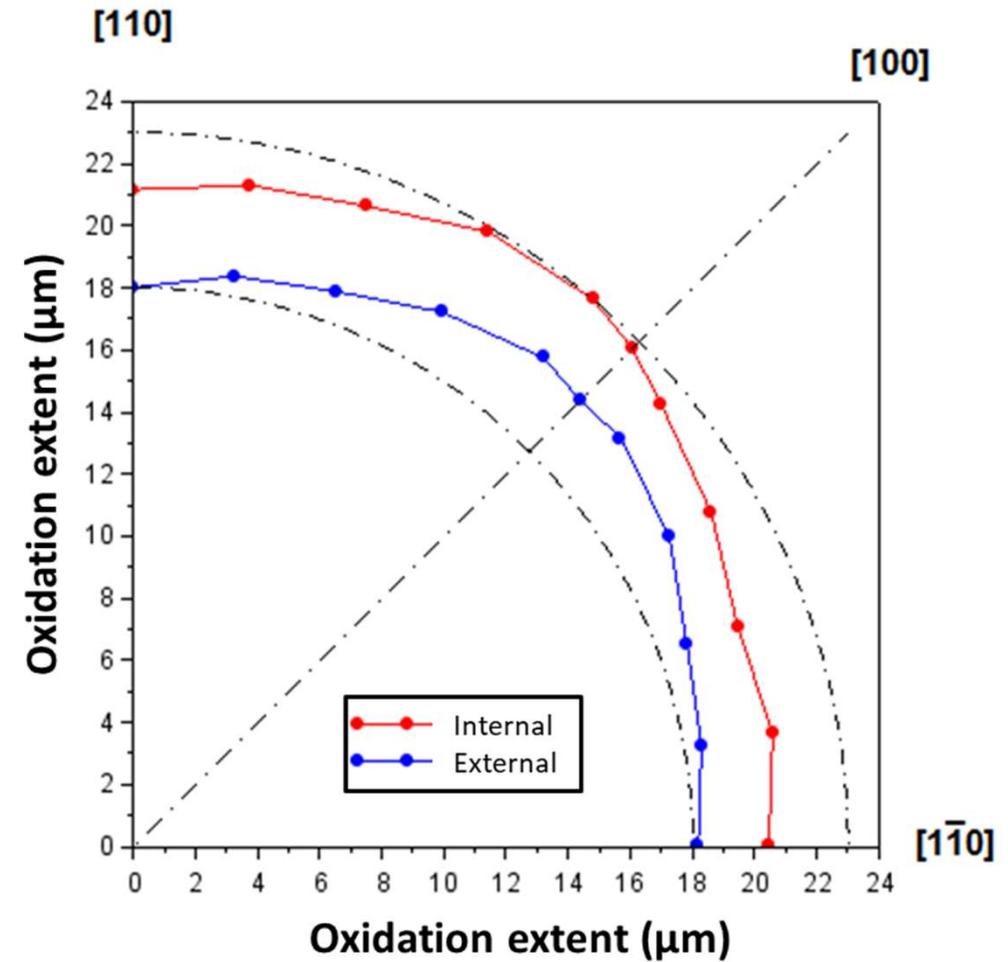
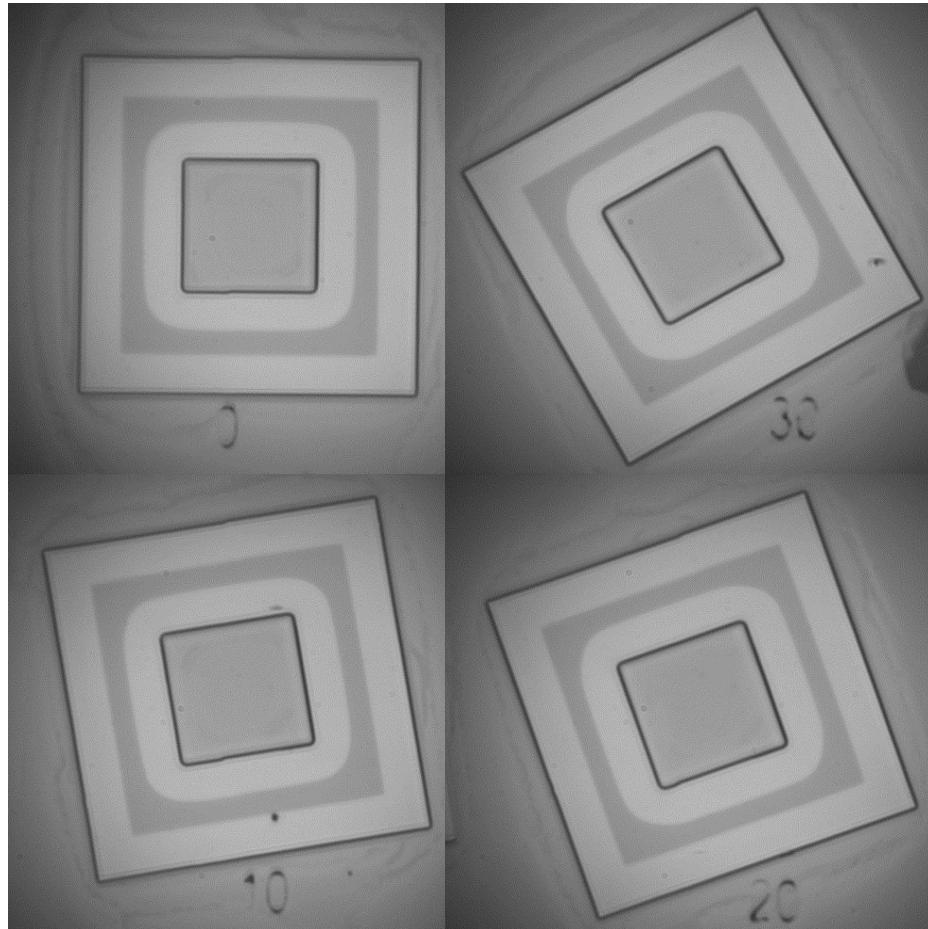


Aperture shape \neq Mesa shape

III-V oxidation anisotropy

Measuring in-plane anisotropy

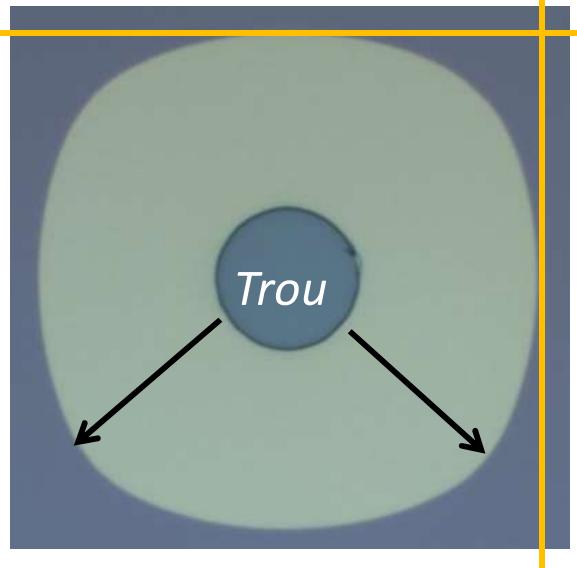
> Direction-dependent measurement



Long-range anisotropic oxidation patterns

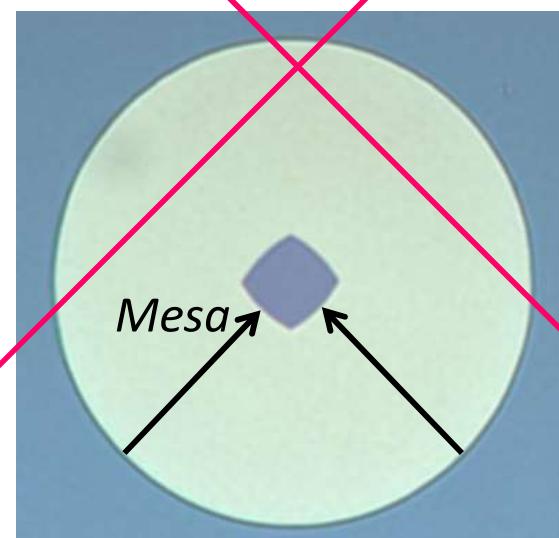
Concave Mesa

Slow-oxidation
planes

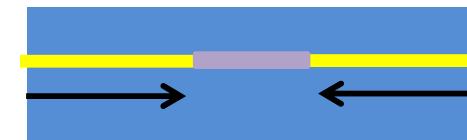


Convex mesa

[100]
[110]



Fast-oxidation
planes



III-V semiconductor oxidation follows Jaccodine's rules* (wet etching)

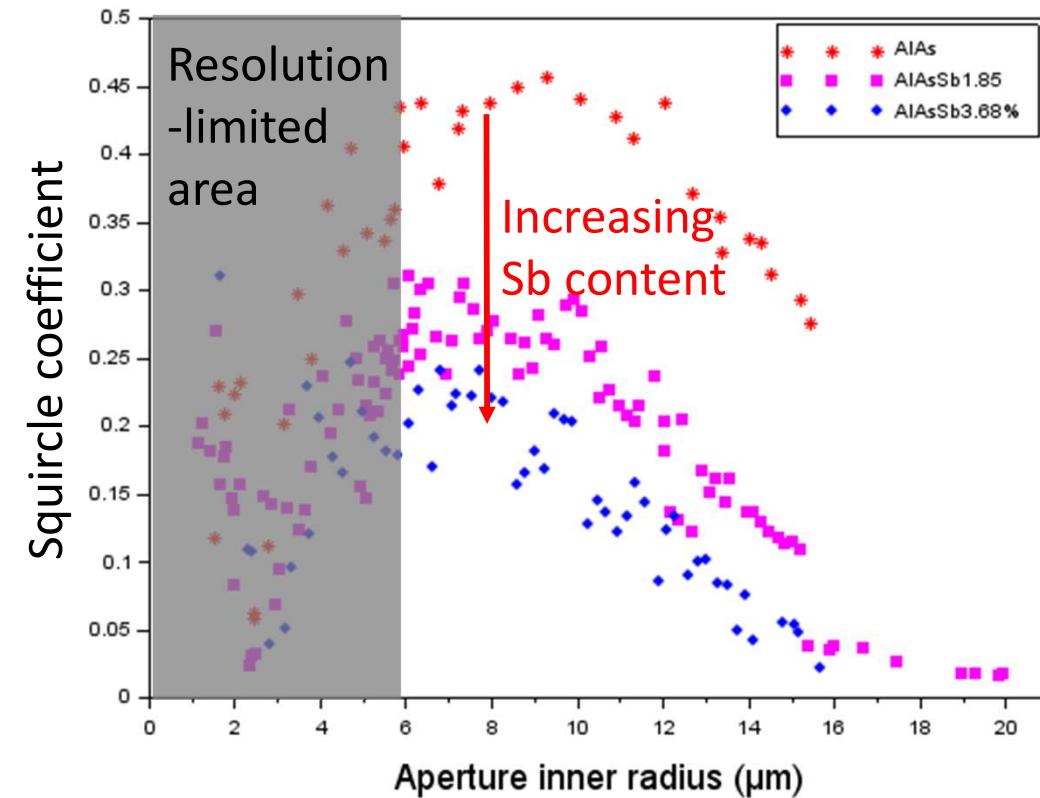
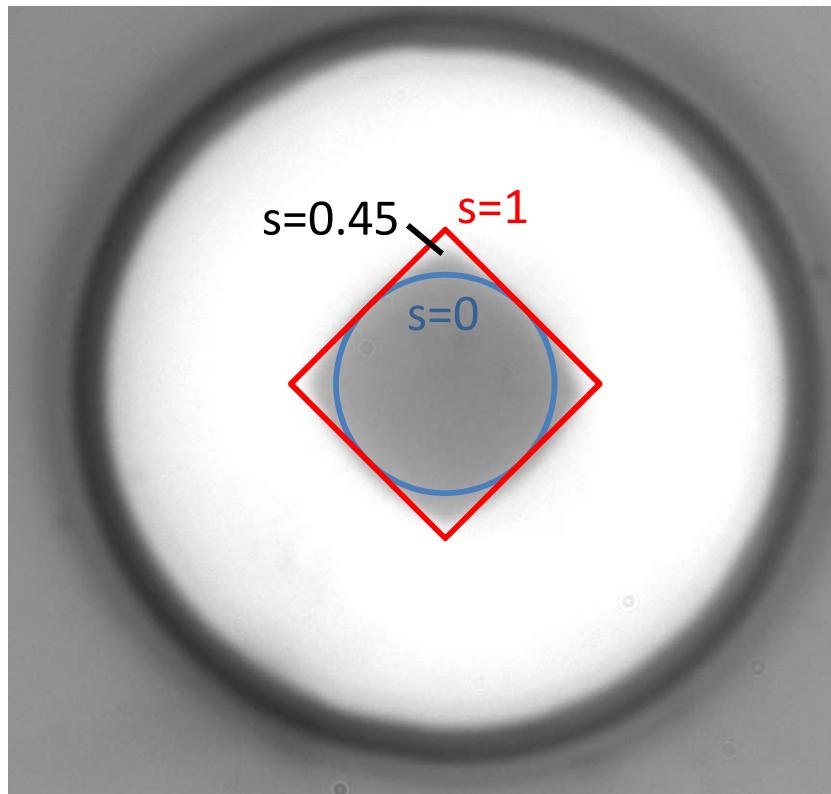
Concave mesa: slow-rate planes control the oxidation contour

Convex mesa : fast-rate planes control the oxidation contour

* R.J. Jaccodine, *J. Appl. Phys.*, **33** (8), 2643 (1962) ---- G. Lafleur, PhD, Université Paul Sabatier (2016)

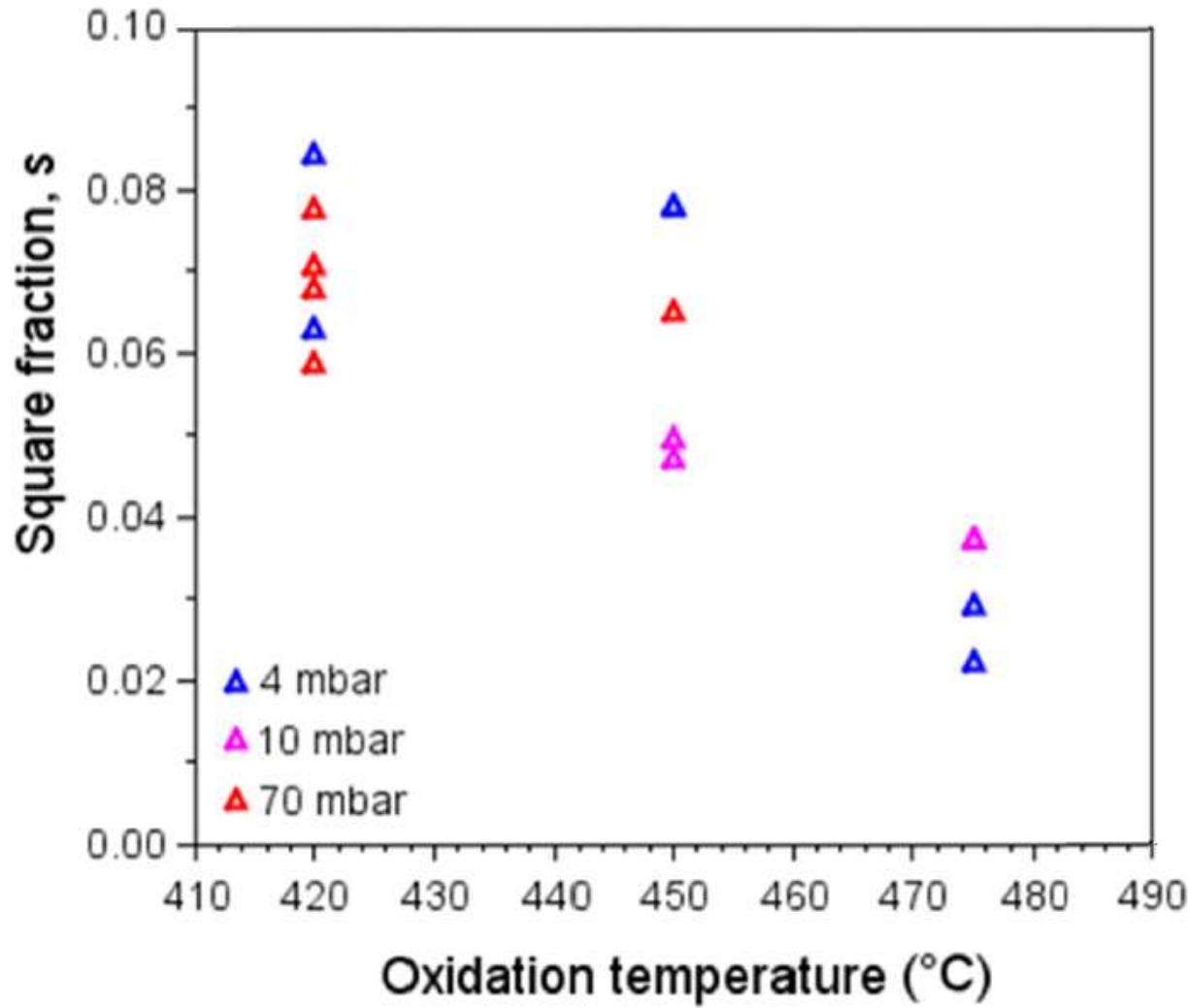
Measuring in-plane anisotropy

- > Oxidation from circular mesas
- > Ad-hoc shape fitting using squircles (rectellipses)



S. Calvez et al, *AIP Advances*, **11**, 125010 (2021);

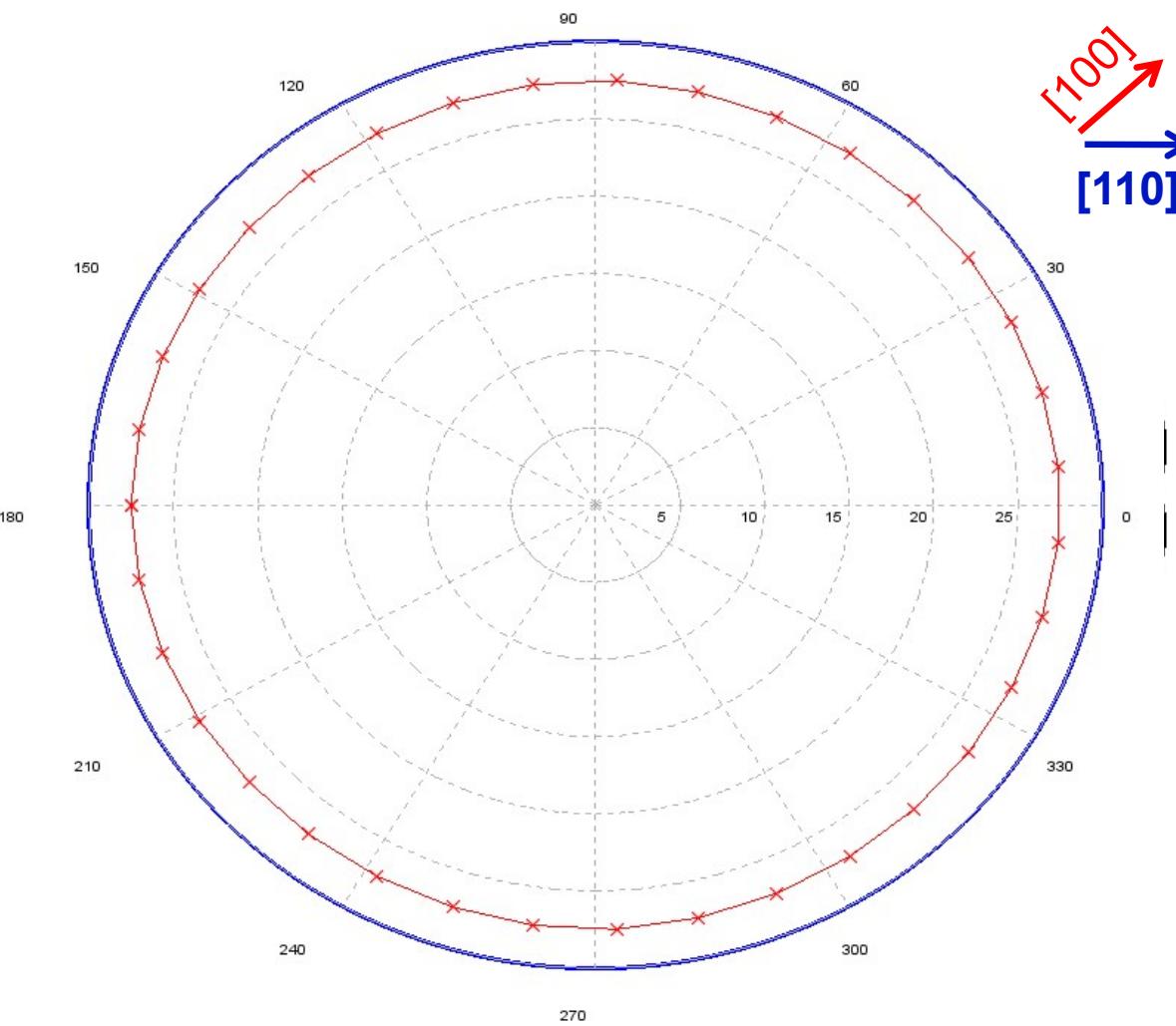
Controlling AlOx anisotropy: Process



- > Process parameters
 - Pressure
 - Wafer temperature
 - H₂O flow
- > Reduced anisotropy at high temperatures (diffusion-limited)
- > Not fully isotropic process

G. Lafleur et al, *Opt. Materials Express*, **8** (7), 1788 (2018)

Controlling AlOx anisotropy: Forward Model



➤ Model Principles

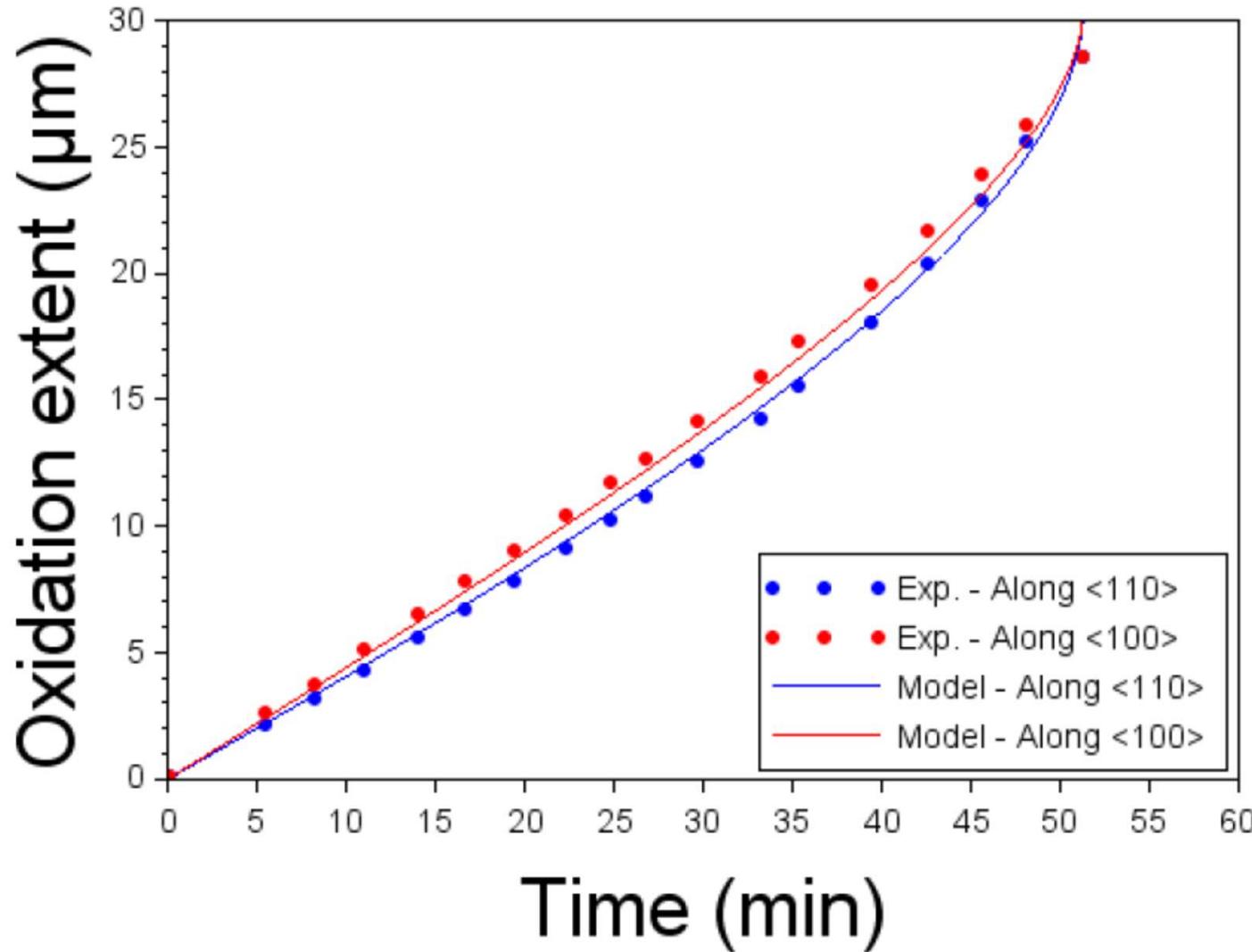
- Iterative model
- Isotropic diffusion
- Uniform concentration at the oxide aperture
- Point-like anisotropic oxidation reactions

$$k(\theta) = k_{moy} \left(1 - \frac{b}{2} + b \sin^2(2\theta) \right)$$

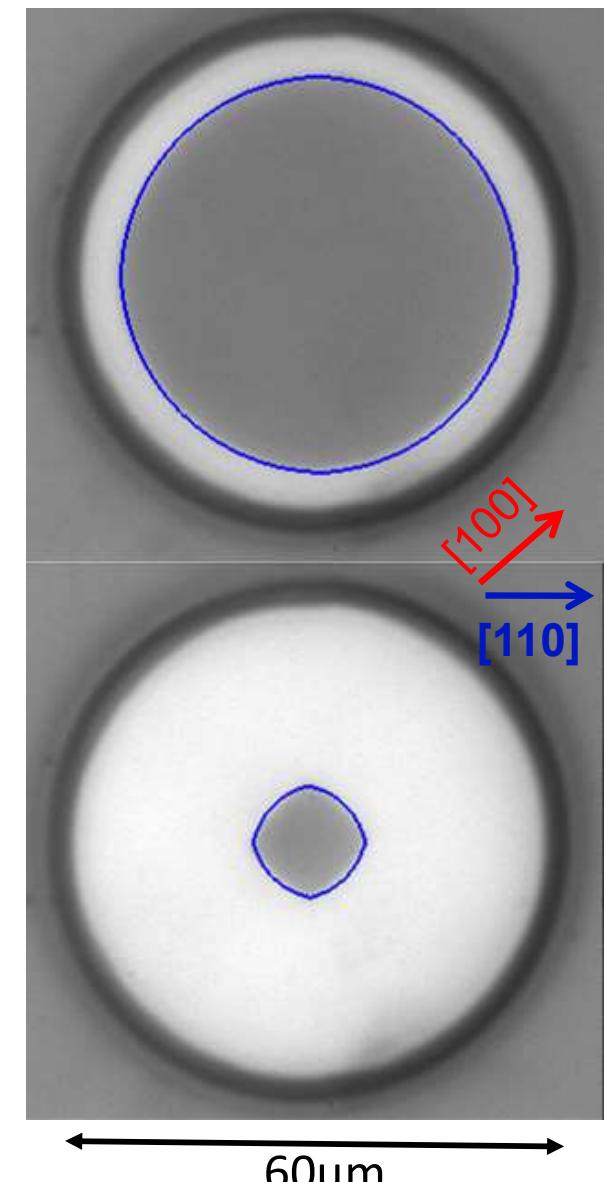
$0 < b < 2$

S. Calvez et al, *Opt. Materials Express*, **8** (7), 1762 (2018)

Controlling AlOx anisotropy: Model Results



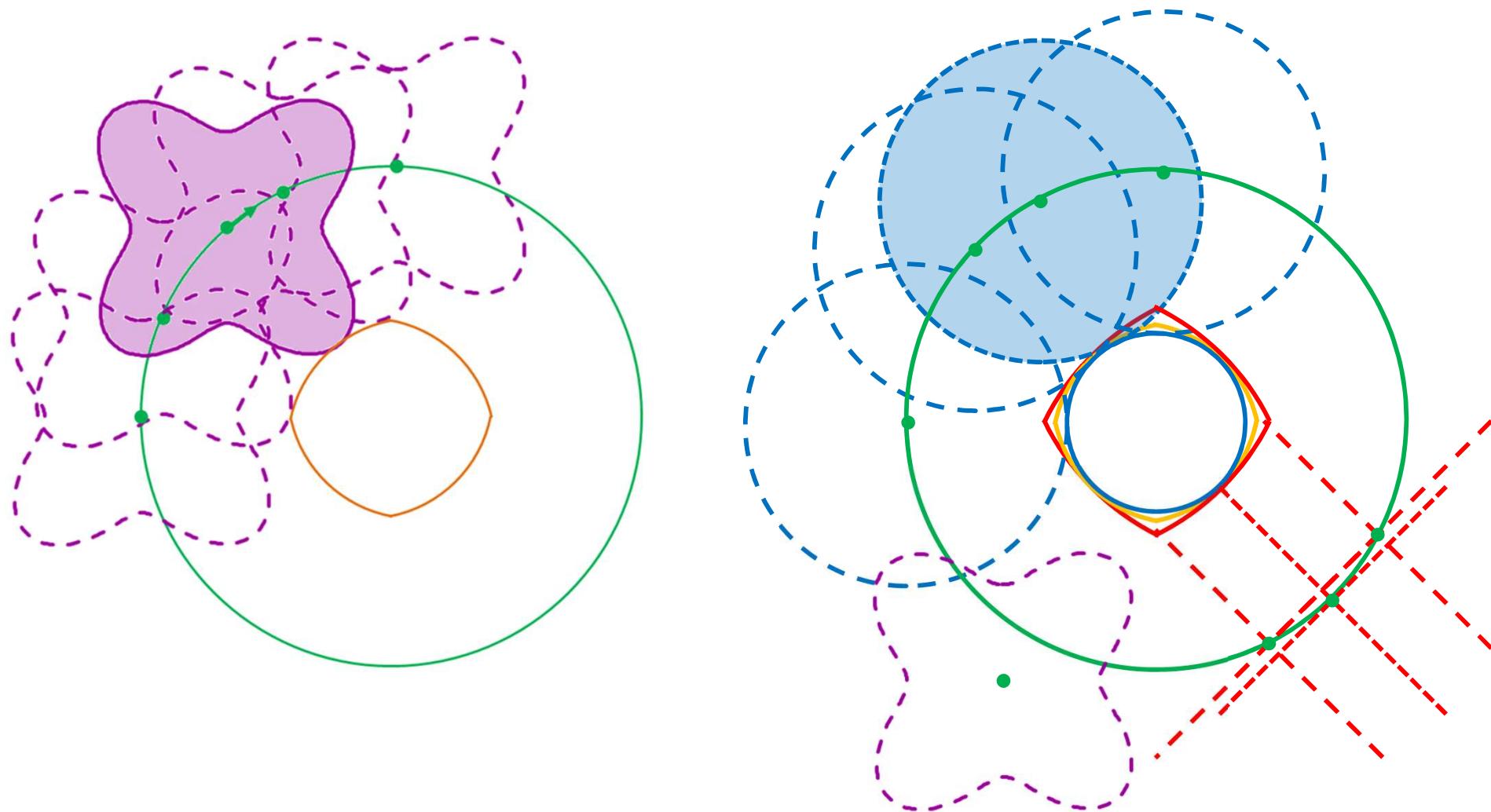
S. Calvez et al, *Opt. Materials Express*, 8 (7), 1762 (2018)



AlOx anisotropy: Mesa shape prediction

- > Able to reproduce an anisotropic oxidation
- > What about tackling the inverse problem ?
 - Define target aperture shape
 - Find the mesa shape for a set oxidation time

Controlling AlOx anisotropy: Forward Model



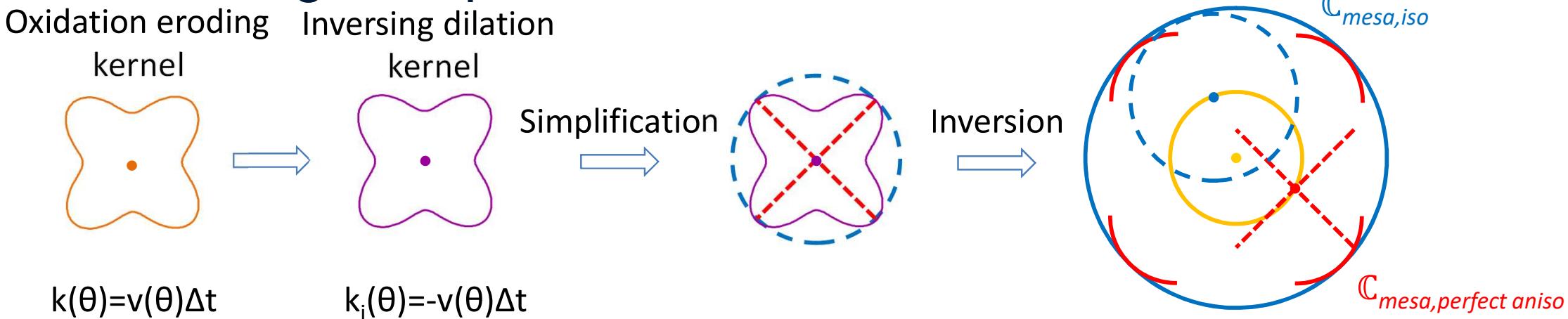
Oxide aperture is bounded by isotropic and perfectly-anisotropic shapes

S. Calvez et al, *Semicon. Sc. Technol.*, **34**, 015014 (2019)

Controlling AlOx anisotropy: Inverse Model

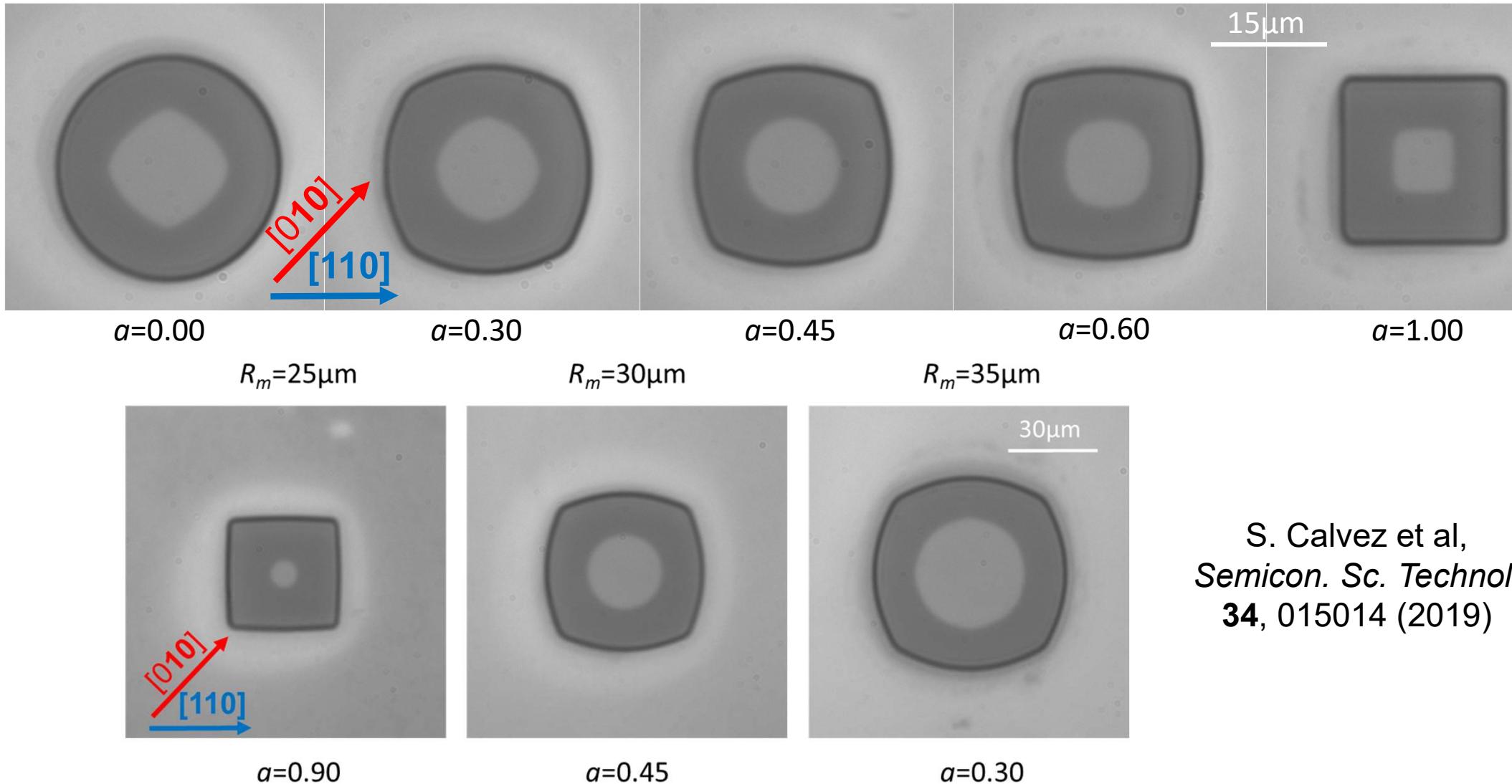
> Inversion: mesa to obtain a given aperture

- Single-step erosion



- Simplification to avoid detailed kernel assessment
- Appropriate shape is bounded by isotropic and perfectly-anisotropic cases

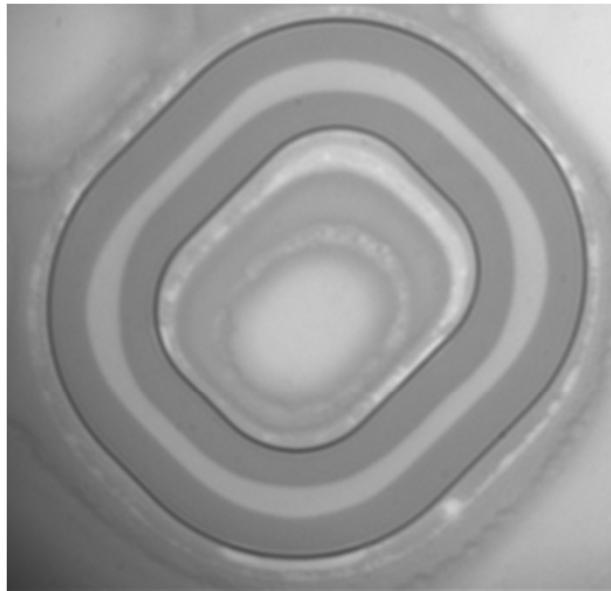
Controlled anisotropy: Inverse Model Results



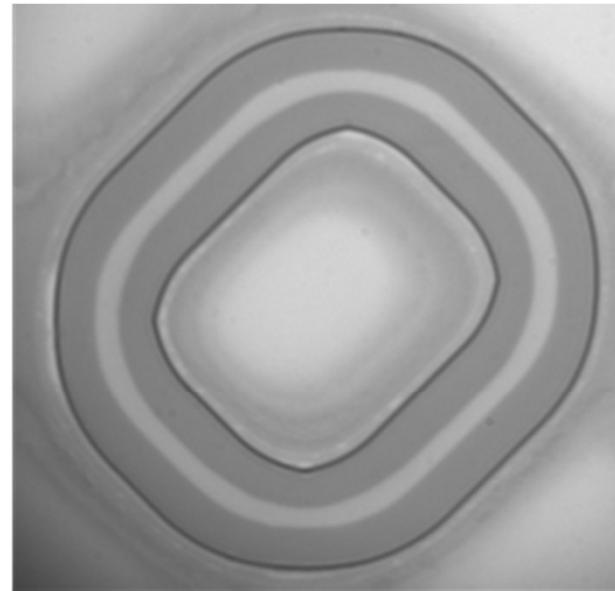
Successful for inward-progressing oxidation

Controlled anisotropy: Inverse Model Results

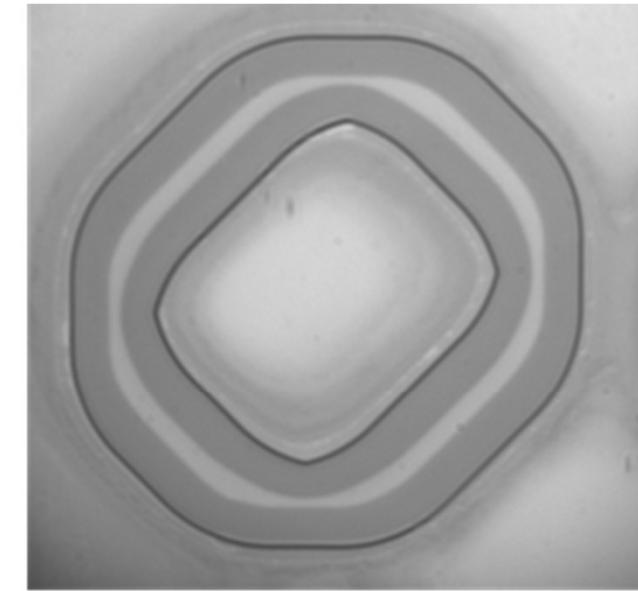
- > Extension for use in photonics integrated circuits
 - Address inwards & outwards oxidation



$a_{in} = a_{ext} = 0.00$



$a_{in} = a_{ext} = 0.35$



$a_{in} = a_{ext} = 1.00$

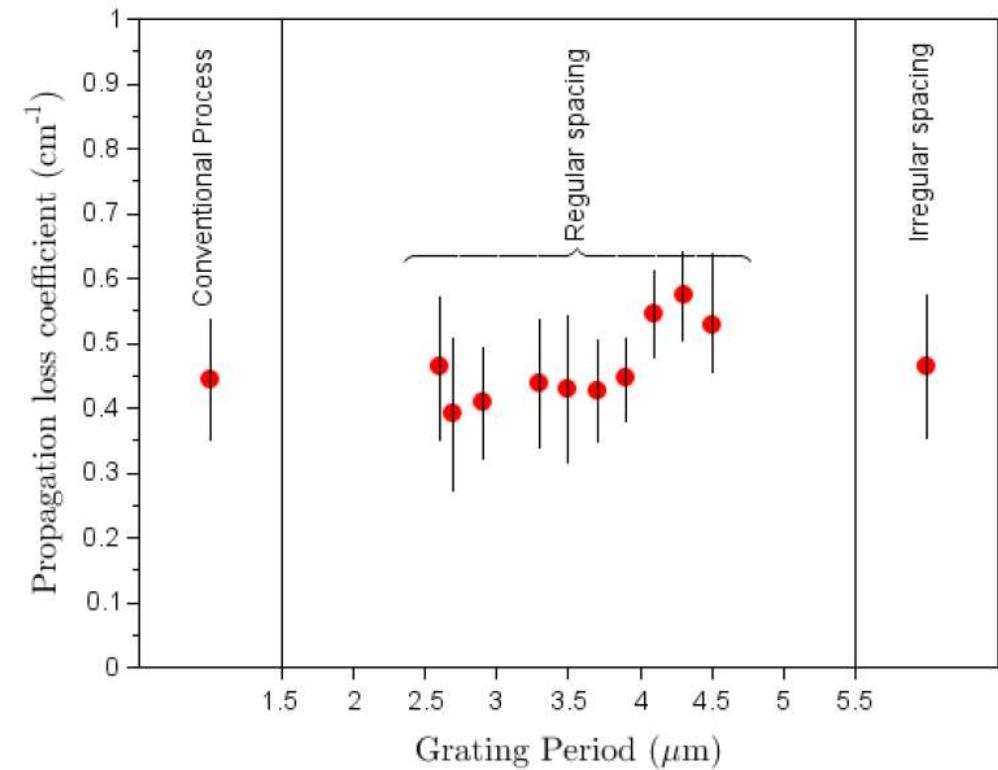
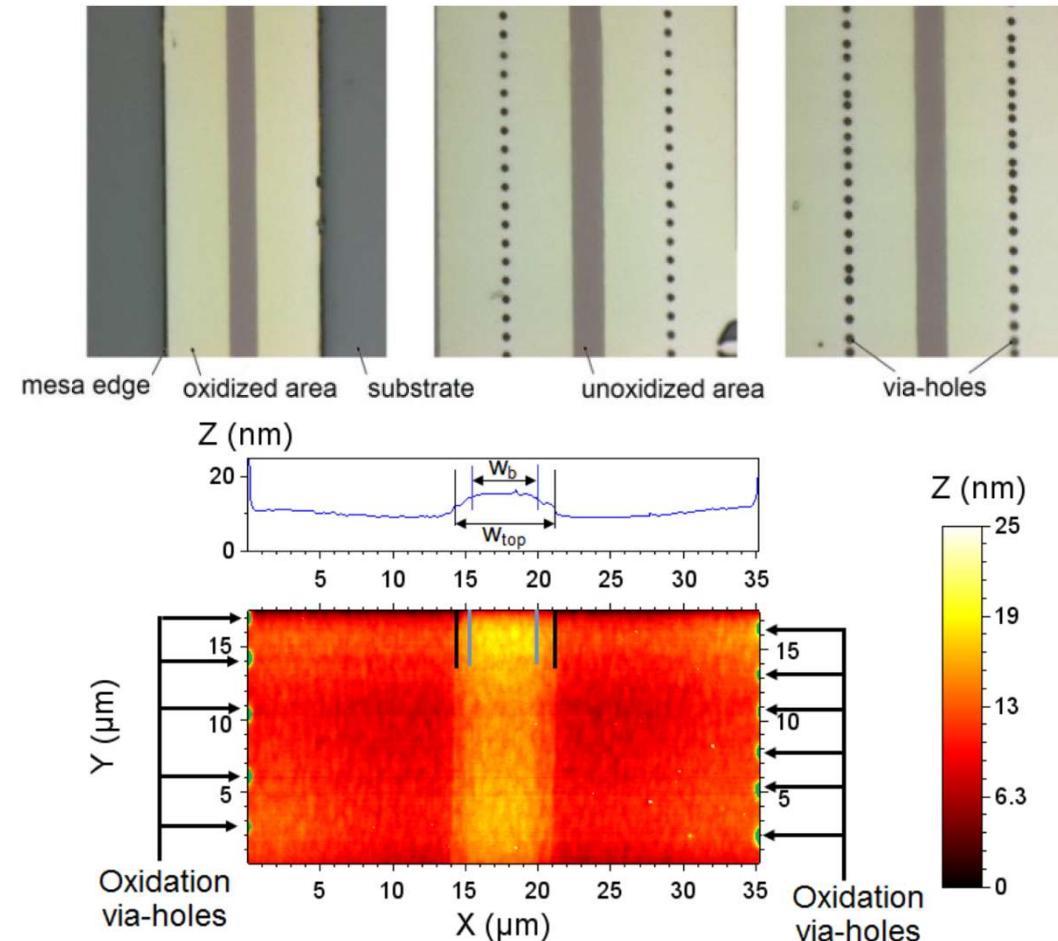
S. Calvez et al, *International Conference on Transparent Optical Networks*, Invited Talk Th.C5.1, (2019).

Inherent oxidation anisotropy: conclusions

- > Defined oxidation anisotropy quantification methods
- > Oxidation process conditions (temperature) and layer composition can influence the anisotropy
- > Oxidation of circular mesas can be reproduced using erosion-based model
- > Inverse-problem (mesa design) can be tackled to create circular apertures and curved waveguides

- > Inherent anisotropy properties
 - Subject to crystalline orientation
 - Relatively weak anisotropy ($v_{\text{fast}}/v_{\text{slow}} < \sim 1.1$)
 - Oxide aperture with smooth contours

Oxidation smoothing effect



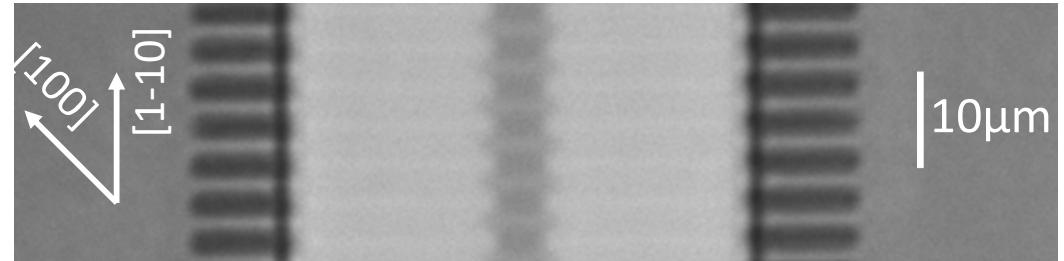
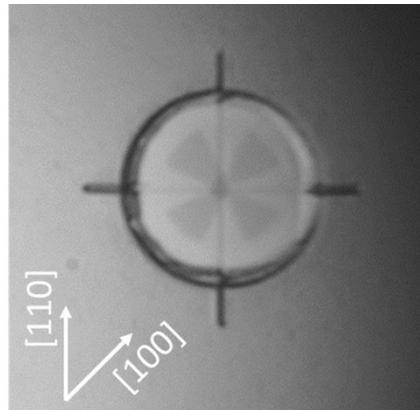
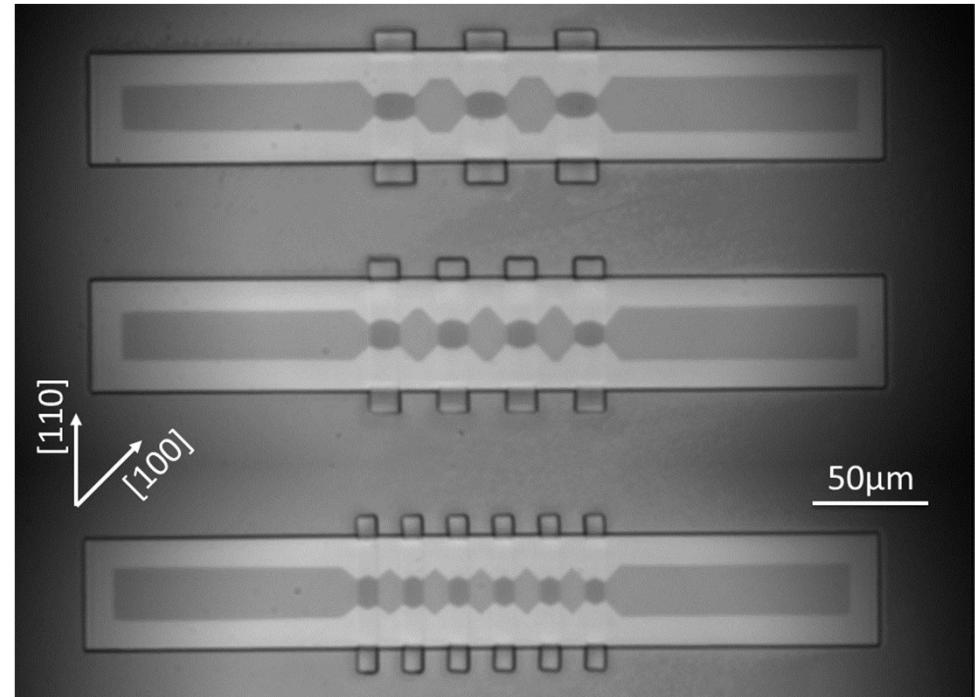
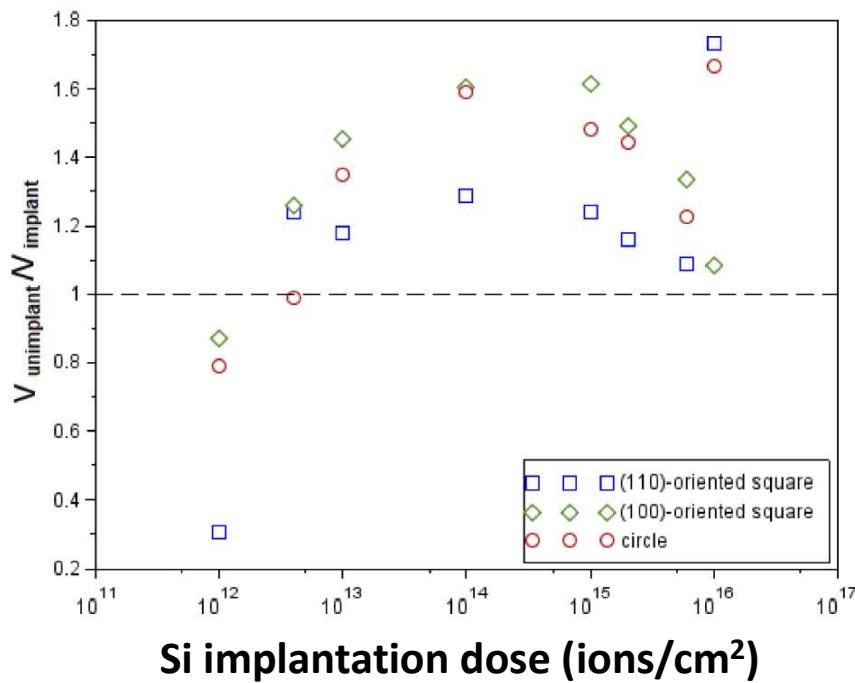
Oxidation diffusive nature prevents (sharply)-corrugated edges

S. Calvez et al, *Opt. Express*, **25** (16), 19275 (2017)

Artificial oxidation anisotropy

- > Interest for artificial anisotropy
 - Oxide aperture with sharp contours
 - Waveguides with side (DFB) gratings
 - Closely-packed matrix of VCSELs
- > How to implement local oxidation anisotropy ?
 - Local modification of composition : implantation of Ga, As (L.-H. Laih et al, *IEEE PTL*, **16** (6), 1423 (2016))
 - Local electrical conductivity change: doping (Si, C) (F. A. Kish, et al, *Appl. Phys. Lett.* **60**(25), 3165–3167 (1992).)
 - Generation of defects ((impurity-free) vacancy-disordering) (T. Gi et al, *Jpn. J. Appl. Phys.* **55** (11), 110303 (2016))

Artificial oxidation anisotropy



S. Calvez et al, *Opt. Mater. Express* **11**, 3600 (2021).

Conclusions

- > III-V-semiconductor oxidation : a ~30-year history
- > LAAS Contributions
 - Furnace with in-situ monitoring
 - Anisotropic oxidation
 - Methods were defined to quantify the anisotropy
 - Oxidation process conditions (temperature) and layer composition can influence the anisotropy
 - Oxidation of circular mesas can be reproduced using erosion-based model
 - Inverse-problem (mesa design) can be tackled to create circular apertures and curved waveguides
 - Artificial anisotropy allows the creation of « unusual » oxidation patterns

Acknowledgements and discussion

> Thank you for your attention !

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> Any questions ???